



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Shinji TAKEDA et al.) Atty. Docket: TM&K0007
Serial No. 09/785,436) Group Art Unit: 2829
Filed: February 20, 2001) Examiner: GEYER, S.
For: SEMICONDUCTOR DEVICE AND)
PROCESS FOR FABRICATION) Date: June 27, 2002
THEREOF)

#16/Election
Amtd
Amend
7/8/02

**AMENDMENT (D) AND REQUEST FOR RECONSIDERATION
OF RESTRICTION/ELECTION REQUIREMENT**

BOX: NO FEE RESPONSE
Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

In response to the official Office Action dated June 4, 2002, please amend the above-captioned application, as follows:

IN THE CLAIMS

Please add new claims 61 and 62 as follows:

61. (NEW) A semiconductor device comprising a support member, a semiconductor chip, an attaching member for attaching the semiconductor chip to the support member, and an encapsulant resin encapsulating the support member, the semiconductor chip and the attaching member, wherein:

the attaching member is a cured product of a die-bonding material;

the die-bonding material is a film comprising one or more resins selected from the group consisting of silicone resin, acrylic resin, polyimide resin and epoxy resin; and

the film having a peel strength of 0.5 Kg/5 x 5 mm chip or above at a stage where the

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